

# Electronic Packaging Products Catalog



Design engineers developing electronic products that need to dissipate heat or make many connections in a small space can now choose from a wide range of components that meet their needs. A revised and expanded catalog from Fujipoly gives detailed specifications and performance characteristics of hundreds of silicon electronic packaging components, organized into six major groups.

These groups include elastomeric connectors that offer low resistance, high conductivity, and high density; thermal management materials in sheets, rolls, die-cuts, pads, sleeves, gels, extrusion, and moldings; LCD bezels and connectors in a wide assortment of standard sizes; EMI/RFI shielding materials in die-cut gaskets, sheets, and rolls; fusible tapes in both insulative and conductive formulations; and custom silicone rubber extrusions and complex co-extrusions.

In a large separate section, the catalog provides engineering and installation guidelines for all products.

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